

REMARKS

Favorable consideration of this application, as presently amended, is respectfully requested.

The present preliminary amendment is submitted to place the above-identified application in more proper format under United States practice.

In the preliminary amendment, Claims 3-6 have been amended to no longer recite any improper multiple dependencies. Further, subject matter of the cancelled multiple dependencies is set forth in new dependent Claims 7-16.

The Abstract has also been amended to be in more proper format under United States practice.

The present application is believed to be in condition for a full and thorough examination on the merits. An early and favorable consideration of the present application is hereby respectfully requested.

Respectfully submitted,

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IN THE CLAIMS

- 3. (Amended) The ceramic substrate according to claim 1 [or 2], wherein the thickness of said ceramic substrate is 25 mm or less.
4. (Amended) The ceramic substrate according to [any one of claims 1 to 3] claim 1, wherein said conductor layer is an electrostatic electrode.
5. (Amended) The ceramic substrate according to [any one of claims 1 to 3] claim 1, wherein said conductor layer is a resistance heating element.
6. (Amended) The ceramic substrate according to [any one of claims 1 to 3] claim 1, wherein said conductor layer is any of a chuck top electrode, a guard electrode and a ground electrode.--

Claims 7-16 (New).

IN THE ABSTRACT OF THE DISCLOSURE

--ABSTRACT

[The objective of the invention is to provide a] A ceramic substrate [: wherein] in which even if rapid temperature rising or rapid temperature falling is conducted, no problem of cracking or warp of the ceramic substrate occurs [; wherein, in] .In a case that the ceramic substrate is a ceramic substrate constituting an electrostatic chuck, local dispersion of chuck power is eliminated, in a case that the ceramic substrate is a ceramic substrate

constituting a hot plate, local dispersion of temperature of a wafer treating face is eliminated, [in] and in a case that the ceramic substrate is a ceramic substrate constituting a wafer prober, dispersion of applied voltage of a guard electrode or a ground electrode is eliminated and a stray capacitor or noise can be eliminated. The ceramic substrate [of the present invention] is a ceramic substrate provided with a conductor layer on the surface of the ceramic substrate or inside the ceramic substrate, [wherein:] in which the ratio (t_2/t_1) of the average thickness of the conductor layer (t_2) to the average thickness of the ceramic substrate (t_1) is less than 0.1, and [;] a dispersion of the thickness of the conductor layer to the average thickness of the conductor layer is in a range of -70 to +150%.--

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